

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): S. Tsuchikawa, et al.  
Application No.: TBD  
Filed: October 31, 2003  
For: THERMOSETTING RESIN COMPOSITION AND USE THEREOF  
Expected Group: 1712  
Expected Examiner: D. Aylward

**CLAIM FOR PRIORITY**

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

October 31, 2003

Sir:

Pursuant to the provisions of 35 USC §119 and 37 CFR §1.55, Applicants hereby claim the right of priority based on Japanese Patent Application No. 2001-022266, filed in Japan on January 30, 2001, and Japanese Patent Application No. 2001-040301, filed in Japan on February 16, 2001.

A certified copy of each of the above-identified Japanese Patent Applications was submitted on February 28, 2002, in prior Application No. 10/058,919, filed January 30, 2002.

Respectfully submitted,

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WIS/sjg